

**GLASS PASSIVATED  
SURFACE MOUNT BRIDGE RECTIFIER**

**REVERSE VOLTAGE – 1000 Volts  
FORWARD CURRENT – 2 Ampere**

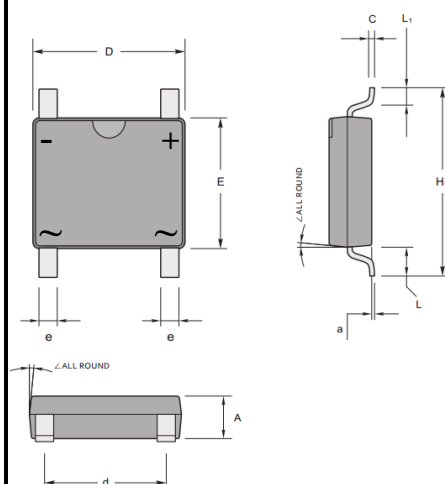
**FEATURES**

- Glass Passivated Chip Junction
- Reverse Voltage – 1000 V
- Forward Current – 2A
- High Surge Current Capability
- Designed for Surface Mount Application
- UL recognized file#E364304

**MECHANICAL DATA**

- Case Material: ABS
- Case Material: Green molding compound, UL flammability classification 94V-0, (No Br. Sb. Cl.)
- Terminals: Solderable per MIL-STD-750, Method 2026
- Weight: 88 mg ( Approximate)

**ABS**



ABS		
DIM	MIN	MAX
A	1.30	1.50
C	0.15	0.22
D	4.90	5.20
E	4.20	4.50
He	6.00	6.40
d	3.80	4.20
e	0.50	0.70
L1	0.60	
∠	7° TYP.	
∠	7° TYP.	
All dimension in millimeter		

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified.

**ABSOLUTE RATINGS**

PARAMETER	SYMBOL	VALUE	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	1000	V
Maximum DC blocking voltage	$V_{DC}$	1000	V
Average rectified output current per device @ $T_C=115^\circ\text{C}$	$I_{(AV)}$	2	A
Peak forward surge current single half sine-wave superimposed on rated load @ $t=8.3\text{ms}$ @ $t=1.0\text{ms}$	$I_{FSM}$	60 120	A
$I^2 t$ rating for fusing ( $t = 8.3\text{ms}$ )	$I^2 t$	14.9	$\text{A}^2\text{S}$
Operating and storage temperature range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**STATIC ELECTRICAL CHARACTERISTICS**

PARAMETER	TEST CONDITION	SYMBOL	MAX.	UNIT
Forward voltage (Note1)	$I_F = 1\text{A}$ $I_F = 2\text{A}$ $T_A = 25^\circ\text{C}$	$V_F$	0.95 1.1	V
Leakage current	$V_R = 1000\text{V}$ $T_A = 25^\circ\text{C}$ $T_A = 125^\circ\text{C}$ (Note1)	$I_R$	5 100	$\mu\text{A}$
Typical junction capacitance (Note 2)		$C_J$	25	pF

**THERMAL CHARACTERISTICS**

PARAMETER	SYMBOL	TYP.	UNIT
Typical thermal resistance (Note 3)	$R_{thJA}$ $R_{thJC}$	60 16	$^\circ\text{C/W}$

**Note :**

- (1) Perform static test after the temperature of oven is steady 20 minutes.
- (2) Measured at 1.0MHz and applied reverse voltage of 4.0V DC
- (3) Thermal resistance junction to case, lead and ambient in accordance with JESD-51.  
Unit Mounted on glass epoxy PC board with 4×1.5"×1.5" ( 3.81×3.81 cm ) copper pad.

REV.3, Aug.-2018,KBDA48

# RATING AND CHARACTERISTIC CURVES ABS210



FIG.1- FORWARD CURRENT DERATING CURVE

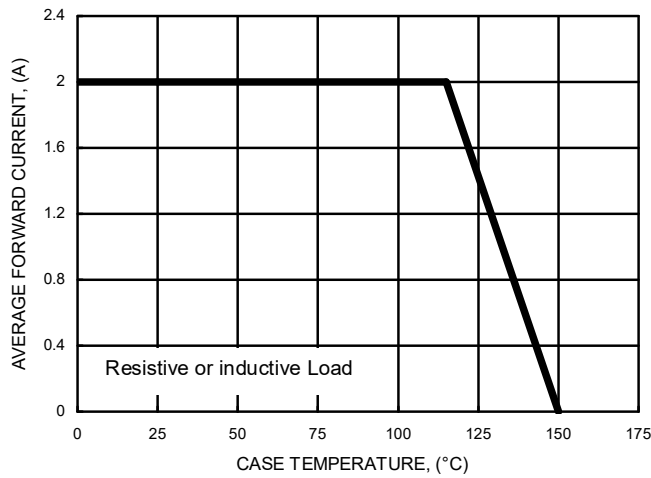


FIG.2- MAXIMUM NON-REPETITIVE SURGE CURRENT

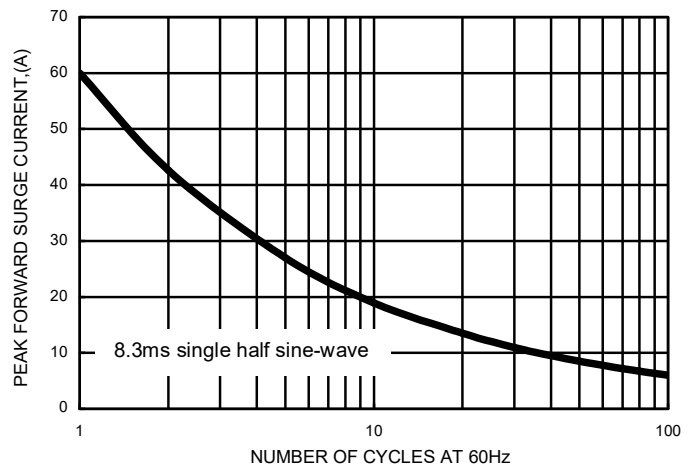


FIG.3- TYPICAL FORWARD CHARACTERISTICS

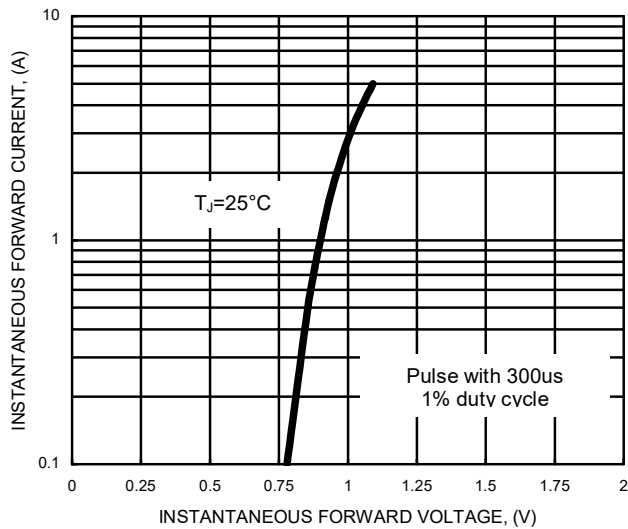


FIG.4- TYPICAL JUNCTION CAPACITANCE

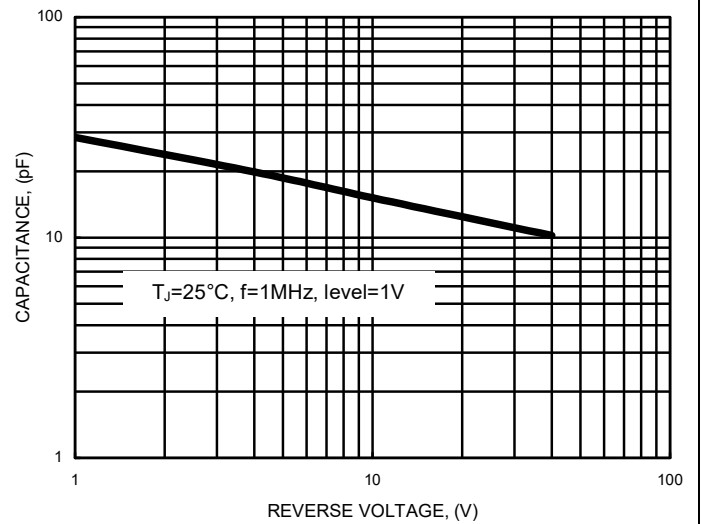
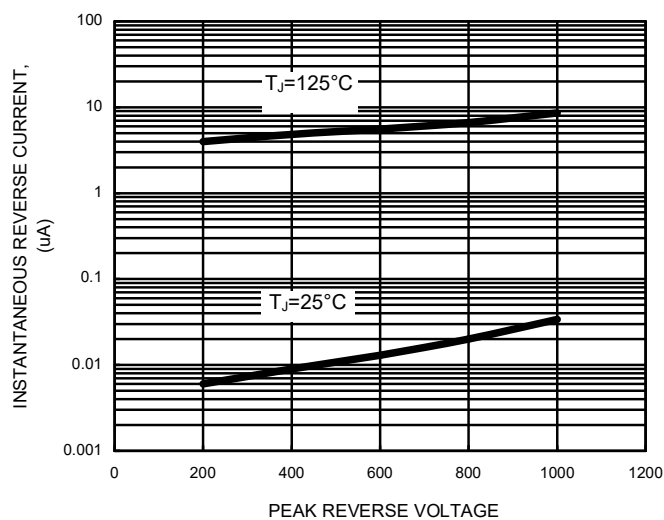


FIG.5- TYPICAL REVERSE CHARACTERISTICS



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